

## Ordering Information

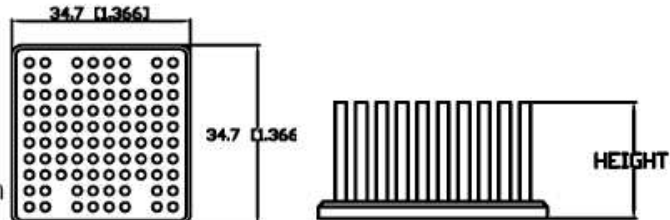
HH=Height		CC=Attachment
12mm	23mm	00 - None
15mm	28mm	01 - Yellow Clip
18mm	33mm	02 - Blue Clip
21mm		03 - Orange Clip
		05 - Special

## BGA Heat Sink Specification

For 35x35 Chip set



- Material : CU1100
- Dimension :  
Foot print : 35x35mm  
Height : 12,15,18,21,23,28,33 mm  
Base (thickness) : 2.6mm



- Finish: Antioxidant Treatment
- Chip set package thickness and clip color  
3.3+/-0.25mm - Yellow clip  
1.7+/-0.25mm - Blue clip  
0.8+/-0.25mm - Orange clip
- Accessory :  
Clip : Plastic (UL94-V0)  
Thermal pad : T710 or others



## Performance

Heat Source (LxW)	15x15
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